2SC2631

Silicon NPN epitaxial planar type

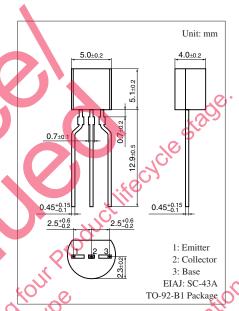
For low-frequency high breakdown voltage amplification Complementary to 2SA1123

■ Features

- Satisfactory linearity of forward current transfer ratio h_{FE}
- ullet High collector-emitter voltage (Base open) V_{CEO}
- Small collector output capacitance (Common base, input open circuited) C_{ob}

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	150	V	
Collector-emitter voltage (Base open)	V_{CEO}	150	V	
Emitter-base voltage (Collector open)	V _{EBO}	5	V	
Collector current	I_{C}	50	mA	
Peak collector current	I_{CP}	100	mΑ	
Collector power dissipation	P _C	750	mW	
Junction temperature	T _j	150	%(0	
Storage temperature	T _{stg}	-55 to +150	x @	
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■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}$

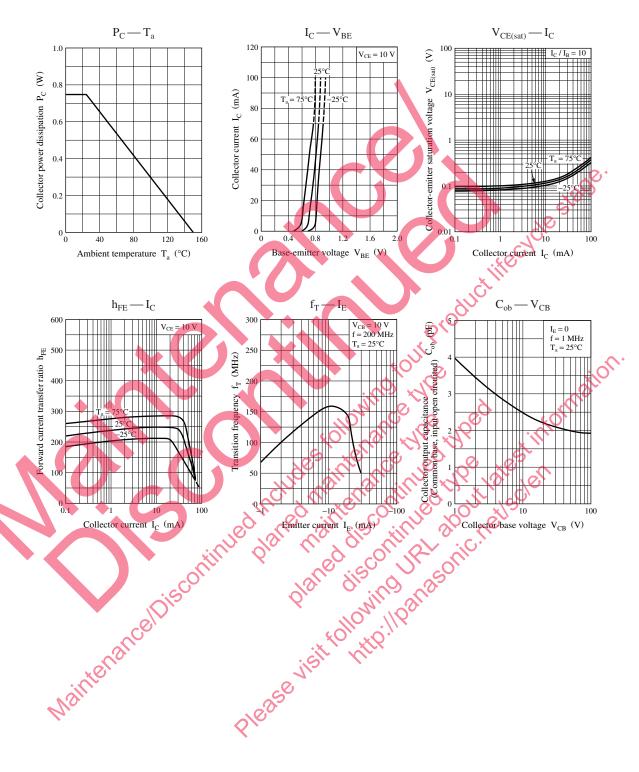
Parameter	Symbol	Conditions	Typ	Max	Unit
Collector-emitter voltage (Base open)	VEO	$I_{\rm C} = 100 \mu \text{A}, I_{\rm B} = 0$	70		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 100 V_{c} I_{E} = 0$		1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 5 \text{ V}, I_C = 10 \text{ mA}$ 130		330	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 30 \text{ mA}, I_B = 3 \text{ mA}$		1	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_{E} = -10 \text{ mA}, f = 200 \text{ MHz}$	160		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		3	pF
(Common base, input open circuited)		isle he			
Noise voltage	NV	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}, G_{V} = 80 \text{ dB}$	150	300	mV
air		$R_g = 100 \text{ k}\Omega$, Function = FLAT			

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S
h_{FE}	130 to 220	185 to 330

Panasonic



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